

IEEE 802.3 Beyond 400 Gb/s Ethernet (B400G) Study Group, 16 Nov 2021 Electronic Plenary Meeting
Unapproved Meeting Minutes, Prepared by Tom Issenhuth, John D'Ambrosia

Session called to order at 10:07 am ET (all times ET), 16 Nov 2021

Meeting called to order by John D'Ambrosia, who chaired the meeting.

Chair showed IMAT information and asked everyone to sign-in as meeting attendance would be taken from IMAT.

Presentation #1 Agenda and General Information

Presenter: John D'Ambrosia

URL: https://www.ieee802.org/3/B400G/public/21_1116/agenda_b400g_211116.pdf

Chair asked if there were any objections to the agenda, there were none, and the agenda (Slide #2) was considered approved.

Minutes – 28 Oct 2021

https://www.ieee802.org/3/B400G/public/21_1028/minutes_b400G_211028_unapproved.pdf

Chair asked if there were any other corrections. There were none. Chair asked if there were any objections to approving the minutes. There were none, and the minutes were considered approved.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –

- IEEE SA Pre-PAR patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Chair presented the (See Slide #22) of the IEEE SA Pre-PAR Patent Policy slides.

Chair presented the second slide (See Slide #24) of the IEEE SA Copyright Policy slides. Chair noted – “By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy.”

Chair presented the second slide (See Slide #27) of the IEEE SA Participation Policy slides. Chair noted – “Participants in the IEEE-SA “individual process” shall act independently of others, including employers. By participating in standards activities using the “individual process”, you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.”

Chair reviewed non-payment of registration fees (See Slide #3)

Chair reviewed key remaining dates for the Study Group. See Slide #6.

D'Ambrosia asked Issenhuth to assume chairing the call, so he could co-present the next presentation. Issenhuth started chairing the call approximately 10:20 am.

Presentation #2 Summary of Comments Received Against P802.3df Project Documentation and Proposed Responses

Presenters John D'Ambrosia

URL https://www.ieee802.org/3/B400G/public/21_1116/dambrosia_b400g_03_211116.pdf

The presentation summarized the submitted comments and proposed responses. The Chair asked the Study Group if there were any additional changes to the PAR and CSD. Changes to the PAR and CSD were captured in slides added to the presentation, which will be posted as 03a. The updated PAR will be presented to the EC on Friday (11/19), once the EC approves the final PAR David Law will send the updated version to the EC administrator who will make the necessary modifications in the online tool.

D'Ambrosia resumed chairing the call at approximately 10:41 am.

The Chair requested that Mr. Law update the PAR on the myProject system. The updated PAR was saved as [Draft_P802.3df_211116.pdf].

The chair reviewed proposed liaison responses to liaisons detailed on Slide #7 of agenda deck.

Presentation #3 Proposed Response to OIF Liaisons

Presenter John D'Ambrosia

URL https://www.ieee802.org/3/B400G/public/21_1116/dambrosia_b400g_02_211116_Redacted.pdf

The proposed response was reviewed and updated per SG discussion and was renamed to IEEE_802d3_to_OIF_b400g_1121_draft.pdf.

Presentation #4 Proposed Response to ITU-T Liaisons

Presenter John D'Ambrosia

URL https://www.ieee802.org/3/B400G/public/21_1116/dambrosia_b400g_01a_211116_Redacted.pdf

The proposed response was reviewed and updated per SG discussion and renamed to IEEE_802d3_to_ITU_b400g_1121_draft.pdf.

Motion #1	Move that the IEEE 802.3 Beyond 400 Gb/s Ethernet Study Group approve: <ul style="list-style-type: none"> • IEEE_802d3_to_ITU_b400g_1121_draft.pdf • IEEE_802d3_to_OIF_b400g_1121_draft.pdf with editorial license granted to the Chair (or his appointed agent) as a liaison communication from the IEEE 802.3 Working Group to ITU-T SG15 and OIF.
M:	Tom Huber
S:	Kent Lusted
Technical (>=75%)	
All (y/n/a)	Motion passes by unanimous consent
Results	Passes

David Law reviewed the updated PAR [Draft_P802.3df_211116.pdf] that will be presented to the EC on Friday.

Motion #2	Move to adopt: <ul style="list-style-type: none"> • The PAR responses to 5.2.b, 7.1 and 7.1.1 in Draft_P802.3df_211116.pdf • The CSD “Broad Market Potential” response, per Slide 7 of dambrosia_b400g_03a_211116.pdf.
M:	Tom Issenhuth
S:	Kent Lusted
Technical (>=75%)	
All (y/n/a)	Passes by unanimous consent
Results	Passes

The chair noted that based on the passing of this motion, he would generate a response to address the comments submitted against the project documentation.

Motion #3	Move to request the IEEE 802.3 WG request the 3rd rechartering of the Beyond 400 Gb/s Ethernet Study Group
M:	Kent Lusted
S:	Jim Weaver
Technical (>=75%)	
All (y/n/a)	Passes by unanimous consent
Results	Passes

Chair reviewed future meetings. See Slide #6.

The meeting adjourned at approximately 11:19 am.

Attendees (per IMAT)

Name	Employer	Affiliation
Akbaba, Enis	Maxim Integrated Products	Maxim Integrated Products
Baldwin, Thananya	Keysight Technologies	Keysight Technologies
Bartlett, Josiah		Maxim Integrated Products
Ben-Artzi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Bernier, Eric		Huawei Technologies Canada; Huawei Technologies Co., Ltd
Bhatt, Vipul	II-VI Incorporated	II-VI Incorporated
Bois, Karl	TE Connectivity	TE Connectivity
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Brown, Blake		University of New Hampshire InterOperability Laboratory (UNH-IOL)
Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.
Calvin, John	Keysight Technologies	Keysight Technologies
Casher, Patrick		Foxconn Interconnect Technologies (FIT)
Chang, Jacky	Hewlett Packard Enterprise	Hewlett-Packard Development Company, L.P.
Chang, Xin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.
Choudhury, Golam	OFS	OFS
D'Ambrosia, John	Futurewei Technologies	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
Deandrea, John	Finisar Corporation	Finisar Corporation
DeSanti, Claudio	Dell	Dell
Dudek, Michael	Marvell	Marvell
Estes, David	Spirent Communications	Spirent Communications
Ewen, John	Marvell	Marvell
FAn, DAWEI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC, Marvell
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
Goodwill, Dominic		Huawei Technologies Canada; Huawei Technologies Co., Ltd
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Hagene, Steffen		TE Connectivity
Haser, Alexandra	Molex Incorporated	Molex Incorporated
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	Intel Corporation	Intel Corporation
Hegde, Rajmohan	Broadcom Corporation	Broadcom Ltd.
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hu, Kangmin		Innogrit
Huang, Kechao		Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Hutchins, Jeff	Ranovus	Ranovus

Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Canada; Huawei Technologies Co., Ltd
ISHIBE, KAZUHIKO	Anritsu Company	Anritsu Company
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Jackson, Kenneth	Sumitomo Electric Device Innovations, USA	Sumitomo Electric Industries, LTD
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kamino, John	OFS	OFS
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
Kawatsu, Yasuaki	APRESIA Systems	APRESIA Systems
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Kim, Yongbum	Tenstorrent	Tenstorrent
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kinningham, Alan	I-PEX CONNECTORS	I-PEX (division of Dai-Ichi Seiko)
Klempa, Michael	University of New Hampshire InterOperability Laboratory (UNH-IOL)	Amphenol Corporation
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Lam, Cedric		Google
Laubach, Mark	IEEE member / Self Employed	IEEE member / Self Employed
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Le Cheminant, Greg	Keysight Technologies	Keysight Technologies
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Levin, Itamar		Intel Corporation
Lewis, David	Lumentum Inc.	Lumentum Inc.
Li, Pei-Rong		MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lingle, Robert	OFS	OFS
Liu, Hai-Feng	HG Genuine	HG Genuine
Liu, Karen	Nubis Communications	Nubis Communications
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Intel Corporation	Intel Corporation
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Mu, Jianwei		Hisense
Muller, Shimon	Enfabrica Corp.	Enfabrica Corp.
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Nakamoto, Edward	Spirent Communications	Spirent Communications
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.

Nicholl, Shawn	Xilinx	Xilinx
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Palkert, Thomas	Macom, Samtec	Samtec-Macom
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Piebler, David	Dell Technologies	Dell
Pittala, Fabio	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Duesseldorf GmbH
Powell, William	INDEPENDENT	INDEPENDENT
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Radhamohan, Rajeshmohan	MAXLINEAR INC	Broadcom Corporation
Rahn, Jeffrey	Facebook	Facebook
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Rea, David		The Siemon Company
Rechtman, Zvi	Mellanox Technologies	NVIDIA Corporation
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Sakai, Toshiaki	Socionext Inc.	socionext
Sambasivan, Sam	AT&T	AT&T
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Shubochkin, Roman	OFS	OFS
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Sprague, Edward	Infinera Corporation	Infinera Corporation
Srivastava, Atul	NEL-America	NTT Electronics
Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
SU, CHANGZHENG		Huawei Technologies Co., Ltd
Sun, Junqing	Credo Semiconductor	Credo Semiconductor
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
Takayama, Kazuya	Nitto Denko Corporation	Nitto Denko Corporation
Tan, Kan	Tektronix, Inc.	Tektronix, Inc.
Theodoras, James	HG Genuine	HG Genuine
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Trowbridge, Stephen	Nokia	Nokia
Ulrichs, Ed	Intel Corporation	Intel Corporation
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xinyuan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Weaver, James	Arista Networks	Arista Networks
Wey, Jun Shan	Verizon Communications	Verizon Communications
Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Young, James	CommScope, Inc.	CommScope
Zhang, Bo	Marvell Technology, Inc	Marvell Technology, Inc
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.